

MDSA Series

SMD Low Profile High Current Molded Inductor

Size 5030



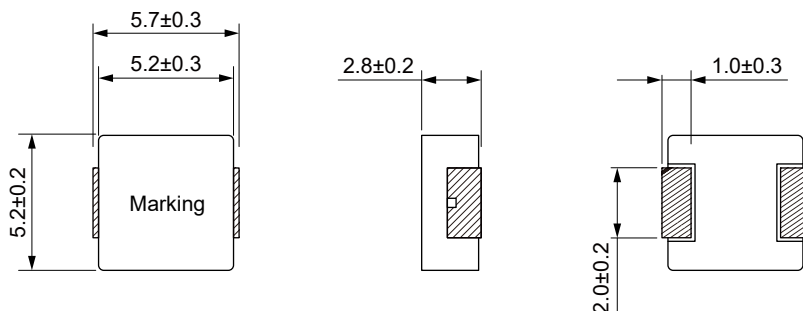
FEATURES

- Shielded construction
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- Ultra low buzz noise, due to composite construction.
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- AEC-Q200 qualified
- Operating temperature: -55 to +155 °C(including self-temperature rise)
- Quantity: 2000PCS

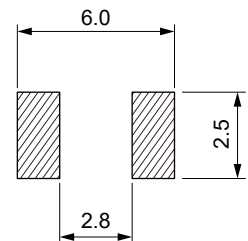
APPLICATION

- Noise filter for various drive circuitry requiring high temp. operation and peak current handling capability.
- Boost-Converter
- Buck-Converter DC/DC

Dimensions: [mm]



Land Pattern: [mm]



Electrical Properties:

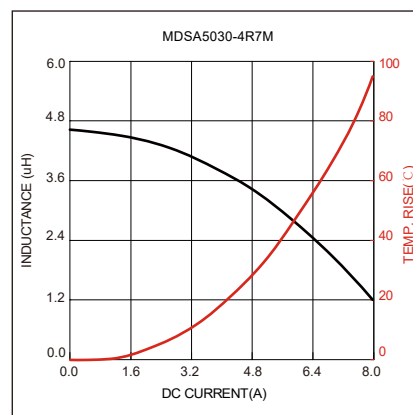
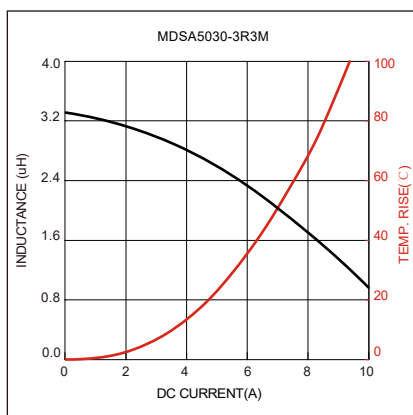
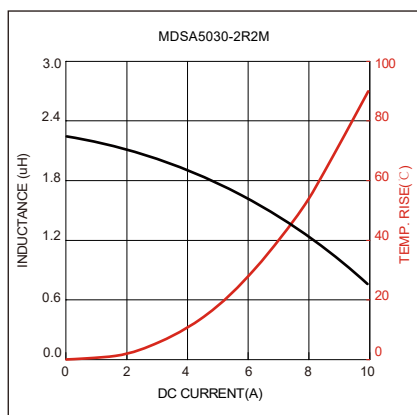
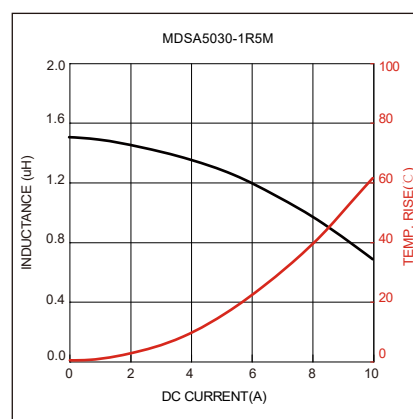
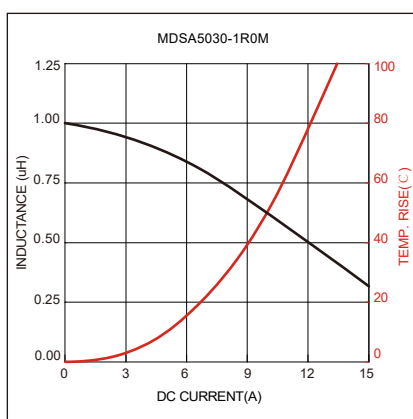
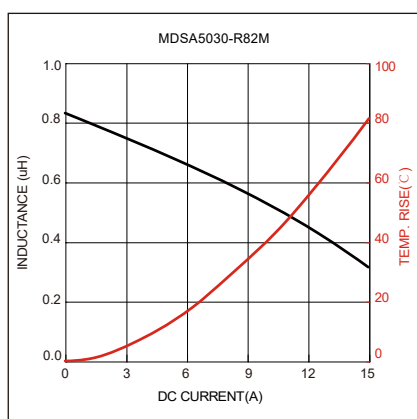
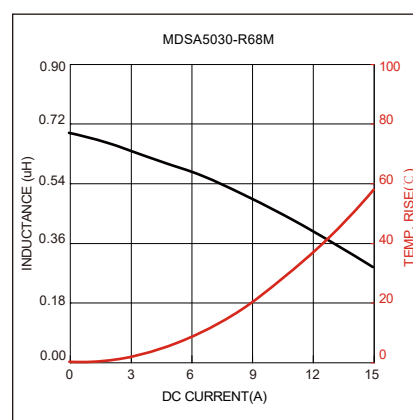
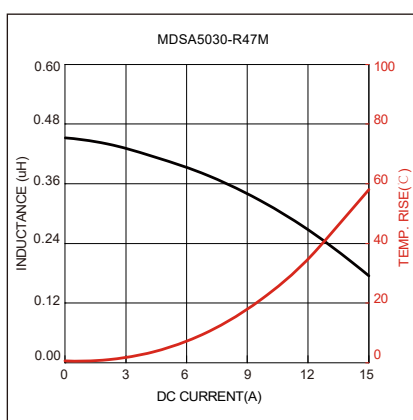
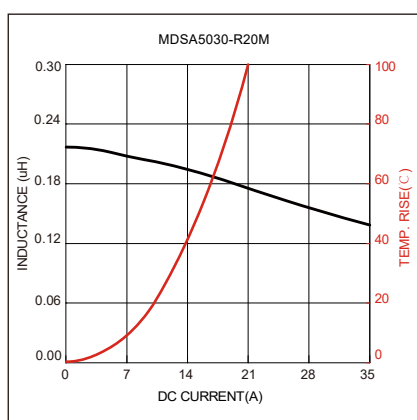
Part No	Inductance @ 100KHz/1V	Tolerance	Temperature Rise Current Typ. (A)	Current Typ. (A)	DC Resistance Typ.	DC Resistance Max.

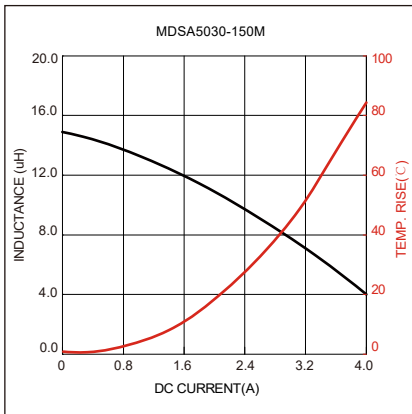
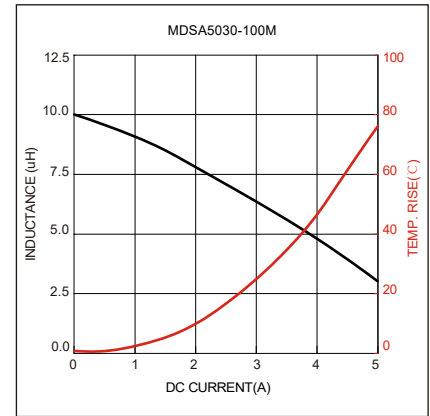
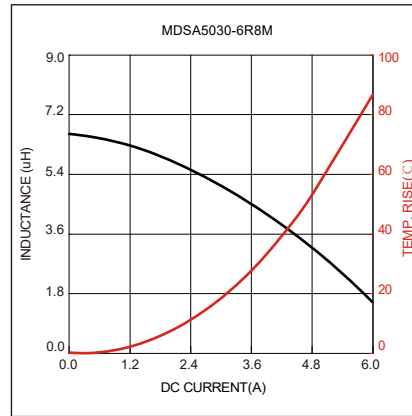
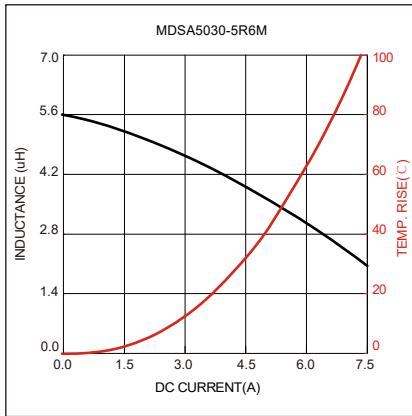
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Saturation Current will cause L to drop approximately 30%

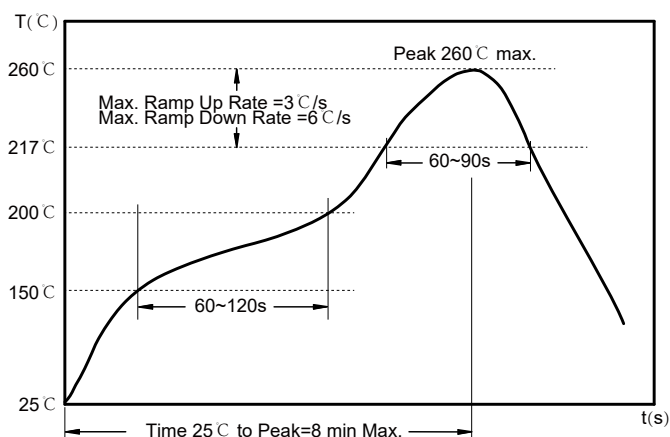
Temperature Rise Current: The actual value of DC current when the temperature rise is $\Delta T=40^{\circ}\text{C}$

Typical Electrical Characteristics:





Soldering Reflow:



Preheat condition: 150 ~200 °C / 60~120 sec.

Allowed time above 217 °C : 60~90 sec.

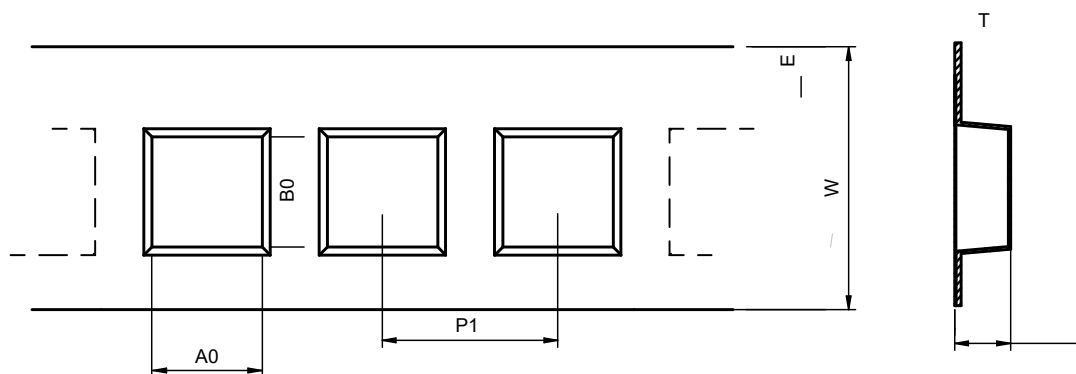
Max temperature: 260 °C .

Max time at max temperature: 10 sec.

Allowed Reflow time: 2x max.

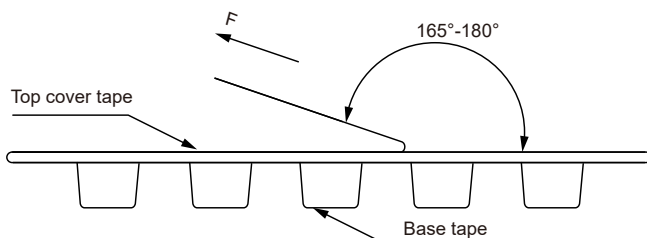
Packaging Information:

Tape Dimension :



Series	A0 (mm)	B0 (mm)	D (mm)	P0 (mm)	P1 (mm)	W (mm)	K0 (mm)	E (mm)	T (mm)
MDSA5030	5.5±0.1	5.9±0.1	1.5±0.1	4.0±0.1	8.0±0.1	12.0±0.3	3.3±0.1	1.75±0.1	0.35±0.05

Peel force of top cover tape:



The peel force of top cover tape shall be between 0.1 to 1.3 N

Product Marking:

Marking	K+Printing (Inductance)
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Reel Dimension: [mm]



Packaging Quantity: